



Product Change Notification

105767 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 105767 - 00
Change Title: Intel® Optical Networking Division, PCN 105767-00, FYI, FAGD16531/41/51/71
Change of Interposer Supplier, Epoxy and Mold Compound
Date of Publication: January 09, 2006

Type of Change Notification:

FYI - (For Your Information)

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Feb 09, 2006
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Description of Change to the Customer:

Due to a fire at one of our sub-contractors in Taiwan, Intel is required to announce a change in the substrate used for the mentioned products below. Please be aware that these products have been discontinued refer to PCN105171-01.

	Current value	Changes to
Interposer	Part# 106232001	Part# Q025A0672450
Interposer supplier	ASE Materials, Chung Li	JCI
Mold Compound	SUMITOMO EME 7720TA	SUMITOMO G700LY
Die attach epoxy	DEXTER QMI 518	ABLEBOND 2000B
Interposer attach epoxy	DEXTER QMI 518	ABLEBOND 2000B

Be advised that inventory of pre-fire parts is limited and orders will be accepted on a first come, first serve basis. Please contact your local Intel Sales Representative for further information.

Customer Impact of Change and Recommended Action:

There is no change in the products form-fit-function or reliability. The product is pin for pin compatible and there are no changes to the ordering information. Product will be available February 2006.

Products Affected / Intel Ordering Codes:

Component Product Table

Affected Product Code	Affected MM#	Post-Affected MM#
FAGD16523100BA	836091	836091
FAGD16524100BA	836092	836092
FAGD16556100BA	834116	834116
FAGD16557100BA	834118	834118

Reference Documents / Attachments:

Document:

Location #:

PCN Revision History:

Date of Revision:

January 9, 2006

Revision Number:

00

Reason:

Originally Published PCN